

Special Issue

Advances in Drying Technologies for Food Processing

Message from the Guest Editors

This Special Issue is dedicated to recent advances in drying and dehydration technologies for food processing, with a particular focus on emerging techniques aimed at preserving food properties. It will address the use of mathematical modeling and computational methods to describe process behavior and enhance drying performance, as well as the effects of innovative drying conditions on food quality and safety. The Special Issue will also provide an overview of both traditional and advanced drying techniques applied in the development of novel processes and products.

Keywords:

- heat and mass transfer
- dehydration
- kinetic modeling
- food engineering
- food quality
- food processing
- hybrid drying
- innovative technologies

Guest Editors

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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